

Product / Process Change Notification



N° 2017-040-A

Dear Customer,

Please find attached our INFINEON Technologies PCN:

Introduction of additional wafer production site with 12" Wafer diameter for IGBT4 1200V (T4) and IGBT HighSpeed 3 (H3) technology.

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before **30. May 2017**.
- Infineon aligns with the widely-recognized JEDEC STANDARD "JESD46", which stipulates:
"Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change."

Your prompt reply will help Infineon Technologies to assure a smooth and well executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.

Infineon Technologies AG
Postal Address Headquarters: Am Campeon 1-12, D-85579 Neubiberg, Phone +49 (0)89 234-0
Chairman of the Supervisory Board: Wolfgang Mayrhofer
Management Board: Dr. Reinhard Ploss (CEO), Dominik Asam, Dr. Helmut Gassel, Jochen Hanebeck
Registered Office: Neubiberg Commercial Register
Amtsgericht München HRB 126492

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► Products affected:

Sales Name	SP N°	OPN	Package
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1200V IGBT4 Modules
Please refer to attached affected product list 1_cip17040a

► Detailed Change Information:

Subject: Introduction of additional wafer production site with
- 12" inch (300mm) wafer diameter capability for IGBT Chips

Reason: Capacity extension and increasing security of supply 1200V IGBT4 and IGBT HighSpeed 3
For IGBT products 12" wafer manufacturing technology is meanwhile the established technology at IFX

Description:	<u>Old</u>	<u>New</u>
	<ul style="list-style-type: none">■ IGBT<u>8" inch:</u><ul style="list-style-type: none">- Front end Villach/ Austria- Front end Kulim/ Malaysia	<ul style="list-style-type: none">■ IGBT<u>8" inch:</u><ul style="list-style-type: none">- Front end Villach, Austria- Front end Kulim/ Malaysia<u>12" inch:</u><ul style="list-style-type: none">- Front end Dresden/ Germany→Target production site front end Dresden/ Germany 12" inch

► Product Identification:

Individual module material number.
See attached list of affected products 1_cip17040a

► Impact of Change:

No impact on electrical performance. Quality and reliability verified by qualification. There is no change in form, fit and function
There is no change in the assembly process at Infineon.

► Attachment:

Affected product list 1_cip17040a

► Time Schedule:

■ Final qualification report:	On request
■ First samples available:	On request
■ Intended start of delivery:	01-Sept-2017 or directly after customer approval

If you have any questions, please do not hesitate to contact your local Sales office.

X-ON Electronics

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Click to view similar products for [Infineon](#) manufacturer:

Other Similar products are found below :

[BSM50GB60DLC](#) [FF600R17KF6C_B2](#) [DD260N12KHPSA1](#) [8500808-9](#) [DATA-94-5231](#) [FD401R17KF6C_B2](#) [FF401R17KF6C_B2](#)
[FF150R12MS4GBOSA1](#) [SPW21N50C3](#) [IRFS31N20D](#) [XMC1100T038X0064AAXUMA1](#) [BUZ30AHXKSA1](#) [FZ400R17KE3HOSA1](#)
[IRF2807](#) [SPA07N60CFD](#) [SPP04N50C3XKSA1](#) [IRL2910](#) [IRFS52N15DHR](#) [BGA231N7E6327XTSA2](#) [IRGP20B60PD](#) [TDA21310XUSA1](#)
[IRF7832](#) [IRF7422D2](#) [IRF7301](#) [IRFR3518](#) [TLE4296G V30](#) [IRFZ24N](#) [IDD05SG60C](#) [IRFP260N](#) [IRF7316](#) [IFX25001TCV10ATMA1](#)
[IRFR3704](#) [IRLIZ44N](#) [BTT6030-2EKA](#) [BSP299 H6327](#) [IFX2931GV33XUMA1](#) [XMC1301T016X0016AAXUMA1](#) [IPU60R2K0C6BKMA1](#)
[IPP80N06S4L-07](#) [BSR302N L6327](#) [IPU60R1K4C6](#) [IRF7805](#) [IRLR8103V](#) [BSL802SNH6327XTSA1](#) [IRFR3910](#) [IRFS59N10D](#)
[IRFS59N10DTRR](#) [EVALM113023645ATOBO1](#) [EVALM11302TOBO1](#) [FD1000R33HE3-K](#)